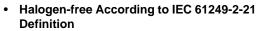


# **Dual N-Channel 20 V (D-S) MOSFET**

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
	$0.086$ at $V_{GS} = 4.5 \text{ V}$	2.6 <sup>a</sup>				
20	0.110 at V <sub>GS</sub> = 2.5 V	2.5 <sup>a</sup>	5.0 nC			
	0.180 at V <sub>GS</sub> = 1.8 V	2.3 <sup>a</sup>				

#### **FEATURES**



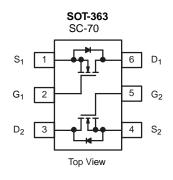


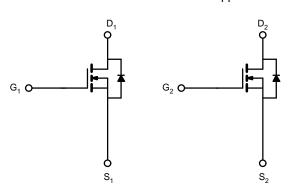
RoHS

- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
- Typical ESD Protection 2100 V HBM
- Compliant to RoHS Directive 2002/95/EC

## **APPLICATIONS**

· Load Switch for Portable Applications





ABSOLUTE MAXIMUM RATINGS	$\bullet$ (1 <sub>A</sub> = 25 °C, unle	ss otherwise no	tea)		
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	20	V		
Gate-Source Voltage		$V_{GS}$	± 12	v	
	T <sub>C</sub> = 25 °C		2.6 <sup>a</sup>		
Continuous Dusin Comment (T. 450 °C)	T <sub>C</sub> = 70 °C		2.2 <sup>a</sup>		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	2.3 <sup>a, b, c</sup>		
	T <sub>A</sub> = 70 °C		1.8 <sup>b, c</sup>	A	
Pulsed Drain Current		I <sub>DM</sub>	8		
Continuous Courses Brain Diade Current	T <sub>C</sub> = 25 °C	1	2.3		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	2.10 <sup>b, c</sup>		
	T <sub>C</sub> = 25 °C		2.70		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C		1.70	10/	
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.5 <sup>b, c</sup>	W	
	T <sub>A</sub> = 70 °C		1.0 <sup>b, c</sup>		
Operating Junction and Storage Temperature Ra	T <sub>.I</sub> , T <sub>sto</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	130	170	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	80	100	- C/VV		

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c.t = 5 s
- d. Maximum under steady state conditions is 220 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A		20		>//00	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 2.3		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.5		2.0	V	
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 8 V			± 25		
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			1	μA	
Zana Onto Valtana B. i. O i		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1	μA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	4			Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 1 \text{ A}$		0.086			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 2.5 \text{ V}, I_D = 1 \text{ A}$		0.110		Ω	
		$V_{GS} = 1.8 \text{ V}, I_D = 0.2 \text{ A}$		0.180		7	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 4 \text{ V}, I_{D} = 1.5 \text{ A}$		4		S	
Dynamic <sup>b</sup>							
Total Cata Charge	Qg	$V_{DS} = 10 \text{ V}, V_{GS} = 8 \text{ V}, I_{D} = 1.5 \text{ A}$		5.0		nC	
Total Gate Charge				3.0			
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 1.5 \text{ A}$		1.0			
Gate-Drain Charge	$Q_{gd}$			2.0			
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	1.9	3.8	kΩ	
Turn-On Delay Time	t <sub>d(on)</sub>			43	65		
Rise Time	t <sub>r</sub>	$V_{DD} = 10 \text{ V, R}_{L} = 8.3 \Omega$		80	120		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 1.2 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		480	720		
Fall Time	t <sub>f</sub>			220	330		
Turn-on Delay Time	t <sub>d(on)</sub>			22	33	ns	
Rise Time	tr	$V_{DD}$ = 10 V, $R_L$ = 8.3 $\Omega$		46	70		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 1.2 \text{ A}, V_{GEN} = 8 \text{ V}, R_g = 1 \Omega$		645	968		
Fall Time	tr			215	323		
Drain-Source Body Diode Characteristic	cs						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C		2.6		۸	
Pulse Diode Forward Current	I <sub>SM</sub>			4		A	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 1.2 A, V <sub>GS</sub> = 0 V		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			9	18	ns	
Body Diode Reverse Recovery Charge Q <sub>rr</sub>		L = 1.2 A dl/dt = 100 A/vo T = 05.00		2	4	nC	
Reverse Recovery Fall Time	Recovery Fall Time $t_a$ $I_F = 1.2 \text{ A, dl/dt} = 100 \text{ A/µs, T}_J =$			5		ns	
Reverse Recovery Rise Time	t <sub>b</sub>	7		4		ns	

#### Notes:

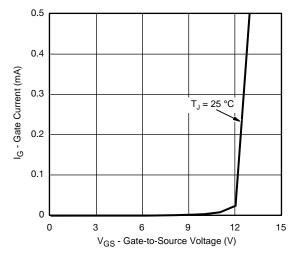
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

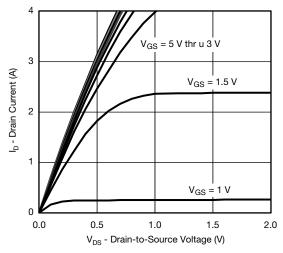
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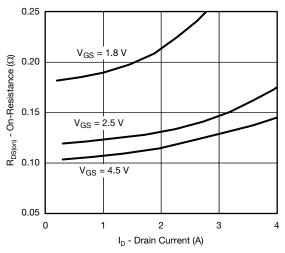
# TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



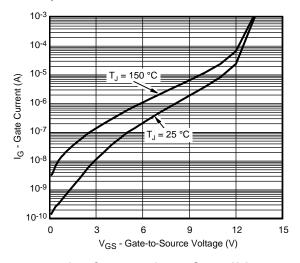
#### Gate Current vs. Gate-to-Source Voltage



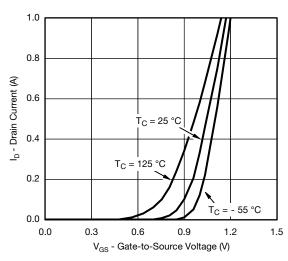
**Output Characteristics** 



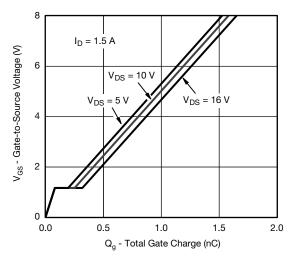
On-Resistance vs. Drain Current



Gate Current vs. Gate-to-Source Voltage



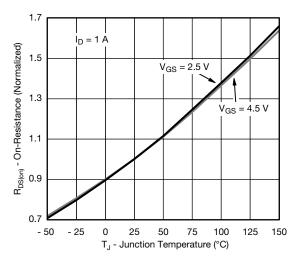
**Transfer Characteristics** 



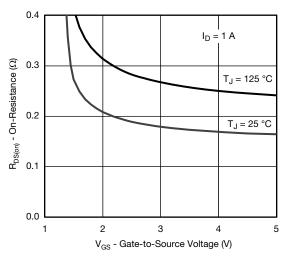
**Gate Charge** 



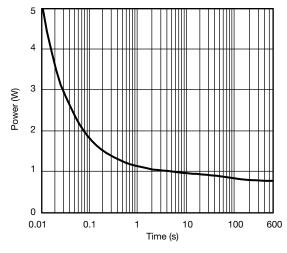
# TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



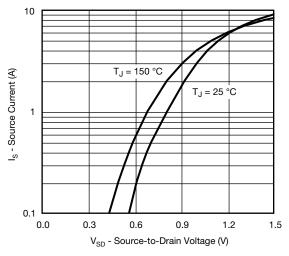
#### On-Resistance vs. Junction Temperature



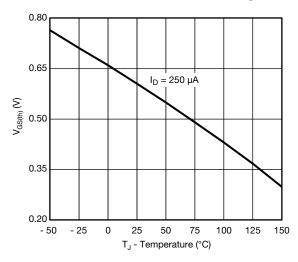
On-Resistance vs. Gate-to-Source Voltage



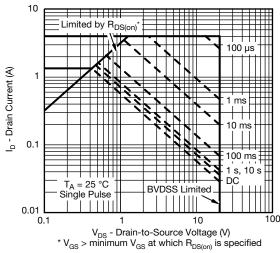
Single Pulse Power, Junction-to-Ambient



## Source-Drain Diode Forward Voltage



#### **Threshold Voltage**

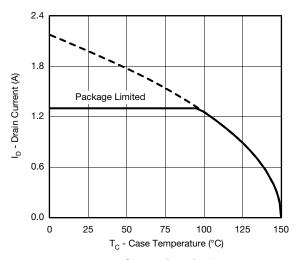


Safe Operating Area, Junction-to-Ambient

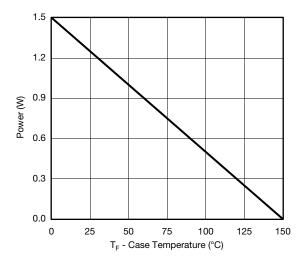
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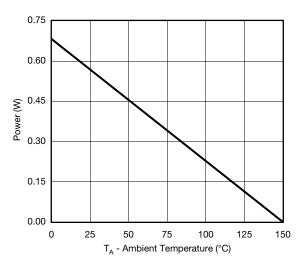
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



#### Current Derating\*







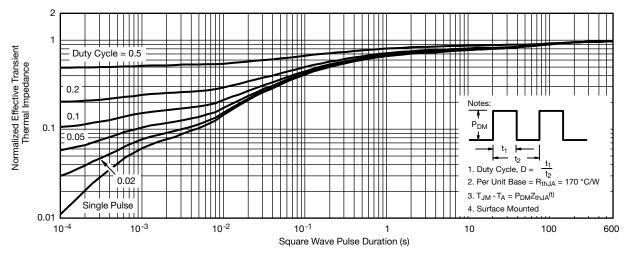
Power, Junction-to-Ambient

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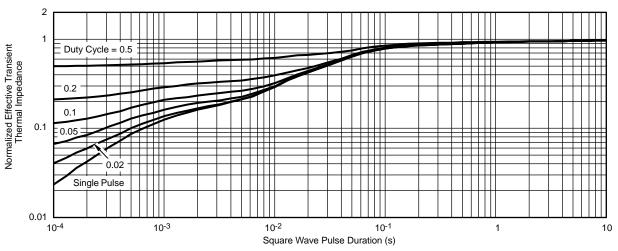
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



# TYPICAL CHARACTERISTICS (25 C, unless otherwise noted)



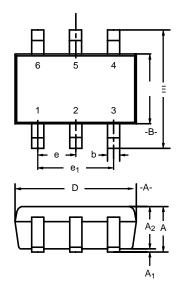
Normalized Thermal Transient Impedance, Junction-to-Ambient

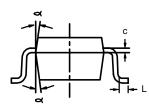


Normalized Thermal Transient Impedance, Junction-to-Foot



# SC-70: 6-LEADS





	MILLIMETERS			INCHES		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.90	_	1.10	0.035	_	0.043
$A_1$	-	-	0.10	-	_	0.004
A <sub>2</sub>	0.80	_	1.00	0.031	_	0.039
b	0.15	-	0.30	0.006	_	0.012
С	0.10	_	0.25	0.004	-	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
Ε	1.80	2.10	2.40	0.071	0.083	0.094
E <sub>1</sub>	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65BSC			0.026BSC		
e <sub>1</sub>	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
a	7°Nom			7°Nom		
				1		

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